



60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
60V	$11m\Omega @ V_{GS} = 10V$	50A

Features and Benefits

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R_{DS(ON)} Minimizes Power Losses
- Low Q_G Minimizes Switching Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- DC Motor Control
- Solenoid Driving
- Power Management Functions

Mechanical Data

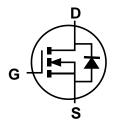
- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (23)
- Terminal Connections: See Diagram Below
- Weight: 0.097 grams (Approximate)



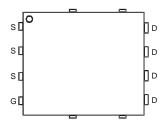




Bottom View



Internal Schematic



Top View Pin Configuration

Ordering Information (Note 5)

Part Number	Case	Packaging
DMNH6012SPSQ-13	PowerDI5060-8	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product_compliance_definitions/.

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5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



☐ I = Manufacturer's Marking
NH6012SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	60	V	
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 7) $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		I _D	50 30	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	I _{DM}	120	Α	
Maximum Continuous Body Diode Forward Current (Note 7)		Is	2.6	Α
Avalanche Current, L = 0.1mH (Note 8)		I _{AS}	45	Α
Avalanche Energy, L = 0.1mH (Note 8)		E _{AS}	100	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 6)		P_D	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	ב	93	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	51	C/VV
Total Power Dissipation (Note 7)		P_D	3.1	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	7	49	°C/W
Thermal Resistance, Junction to Ambient (Note 7)	t<10s	$R_{\theta JA}$	26	
Thermal Resistance, Junction to Case	$R_{ heta JC}$	3.8		
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	$V_{GS(TH)}$	2	_	4	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	8	11	mΩ	$V_{GS} = 10V, I_D = 50A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.7A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{ISS}	_	1,926		pF	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss	_	330	_	pF		
Reverse Transfer Capacitance	C _{RSS}	_	112	_	pF		
Gate Resistance	R_G	_	2.0	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_G	_	16.3	_	nC	V _{DS} = 30V, I _D = 25A	
Total Gate Charge (V _{GS} = 10V)	Q_G	_	35.2	_	nC		
Gate-Source Charge	Q_{GS}	_	7.6	_	nC		
Gate-Drain Charge	Q_{GD}	_	6.9	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	6.4	_	ns	$V_{GS} = 10V, V_{DS} = 30V,$ $R_{G} = 3\Omega, I_{D} = 25A$	
Turn-On Rise Time	t _R	_	11.9	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	_	16.5	_	ns		
Turn-Off Fall Time	t _F	_	5	_	ns		
Body Diode Reverse Recovery Time	t _{RR}	_	28	_	ns	I _F = 25A, di/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q_{RR}	_	23	_	nC		

Notes: 6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

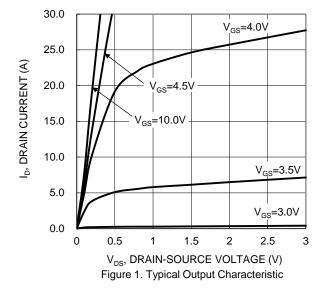
8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25$ °C.

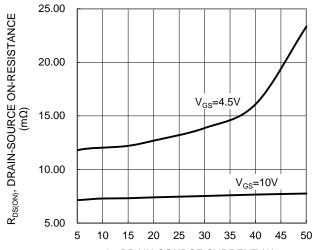
9. Short duration pulse test used to minimize self-heating effect.

April 2016

^{10.} Guaranteed by design. Not subject to product testing.







I_D, DRAIN-SOURCE CURRENT (A)
Figure 3. Typical On-Resistance vs. Drain Current and
Gate Voltage

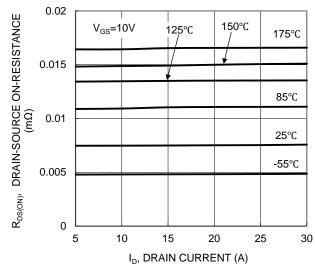
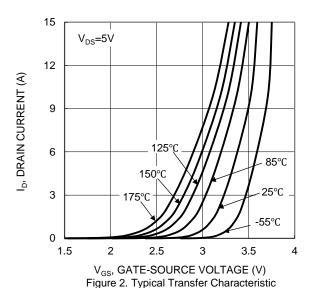
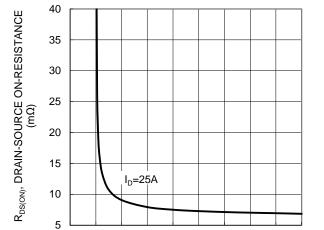


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



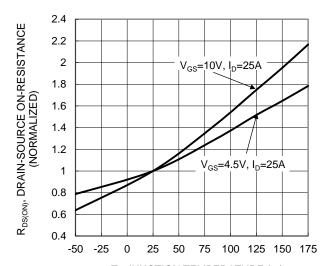


2 4 6 8 10 12

V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

14 16

18



T_{J.} JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Temperature



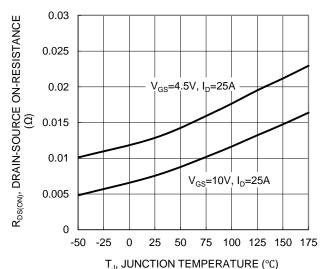


Figure 7. On-Resistance Variation with Temperature

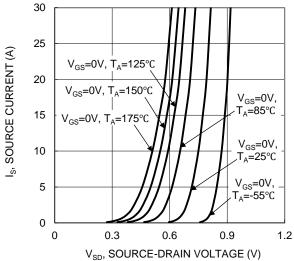


Figure 9. Diode Forward Voltage vs. Current

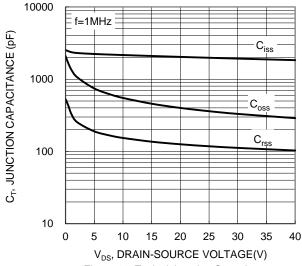


Figure 11. Typical Junction Capacitance

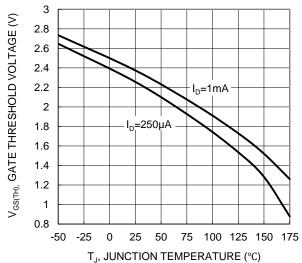
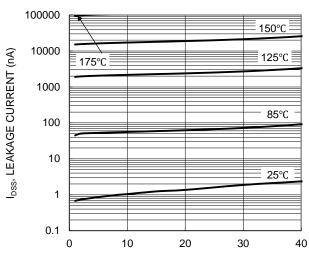


Figure 8. Gate Threshold Variation vs. Junction Temperature



V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Drain-Source Leakage Current vs. Voltage

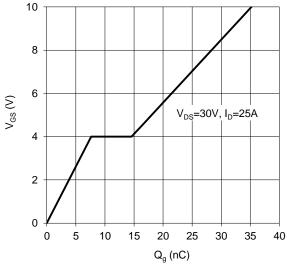


Figure 12. Gate Charge



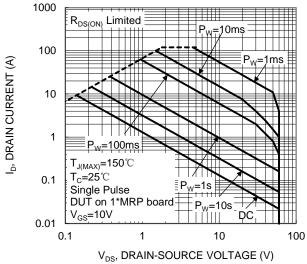


Figure 13. SOA, Safe Operation Area

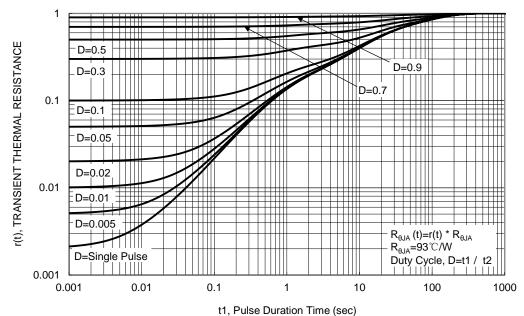


Figure 14. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

Detail A 0(4X) 01 (4X) 01 (4X) 03 (4X) 04 (4X) 05 (4X) 06 (4X) 07 (4X) 08 (4X) 09 (4X)

PowerDI5060-8						
Dim	Min	Max	Тур			
Α	0.90	1.10	1.00			
A1	0.00	0.05	_			
b	0.33	0.51	0.41			
b2	0.200	0.350	0.273			
b3	0.40	0.80	0.60			
С	0.230	0.330	0.277			
D	į.	5.15 BSC	;			
D1	4.70	5.10	4.90			
D2	3.70	4.10	3.90			
D3	3.90	4.30	4.10			
Е	6.15 BSC					
E1	5.60	6.00	5.80			
E2	3.28	3.68	3.48			
E3	3.99	4.39	4.19			
е		1.27 BSC	;			
G	0.51	0.71	0.61			
K	0.51	_	_			
L	0.51	0.71	0.61			
L1	0.100	0.200	0.175			
М	3.235	4.035	3.635			
M1	1.00	1.40	1.21			
Θ	10°	12°	11°			
Θ1	6°	8°	7°			
All	All Dimensions in mm					

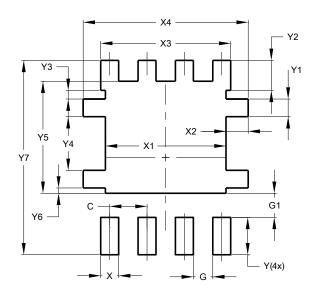
Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

Detail A

PowerDI5060-8

PowerDI5060-8



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Υ	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610



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